## Chapter 2

# Description of Terminal Symbols and Terminology

Contents	Page
1. Description of Terminal Symbols	2-2
2. Description of Terminology	2-3





## 1 Description of Terminal Symbols

#### Main terminals

Terminal Symbol	Description
Р	Main power source Vd input terminal for the inverter bridge.
Ν	P: + side, N: – side
В	Brake output terminal: terminal to connect the resistor for regenerative operation declaration
U	3-phase inverter output terminal
V	
W	
N2	Main power source Vd "negative(-)" input terminal after rectification converter smoothing of the inverter unit (P617, 619)
N1	Terminal for external connection of resistance when the OC level is to be changed (P617, 619)

#### Control terminals

Terminal	P610, P611	P617	P621	Description	
Symbol	P612	P619	P622	Description	
GND U	<1>	<1>	<1>	Control power source Vcc input in the upper arm U phase	
Vcc U	<3>	<3>	<4>	Vcc U: + side, GND U: – side	
Vin U	<2>	<2>	<3>	Control signal input in the upper arm U phase	
ALM U	_	_	<2>	Upper arm U-phase alarm output when the protection circuits are operating	
GND V	<4>	<4>	<5>	Control power source Vcc input in the upper arm V phase	
Vcc V	<6>	<6>	<8>	Vcc V: + side, GND V: – side	
Vin V	<5>	<5>	<7>	Control signal input in the upper arm V phase	
			~6>	Upper arm V-phase alarm output when the protection	
	—	_	101	circuits are operating	
GND W	<7>	<7>	<9>	Control power source Vcc input in the upper arm W phase	
Vcc W	<9>	<9>	<12>	Vcc W : + side, GND W: – side	
Vin W	<8>	<8>	<11>	Control signal input in the upper arm W phase	
ALM W	-	_	<10>	Upper arm W-phase alarm output when the protection circuits are operating	
GND	<10>	<10>	<13>	Control power source Vcc input in the lower arm common	
Vcc	<11>	<11>	<14>	Vcc: + side, GND: – side	
Vin X	<13>	<12>	<16>	Control signal input in the lower arm X phase	
Vin Y	<14>	<13>	<17>	Control signal input in the lower arm Y phase	
Vin Z	<15>	<14>	<18>	Control signal input in the lower arm Z phase	
Vin DB	<12>	-	<15>	Control signal input in the lower arm brake phase	
ALM	<16>	<15>	<19>	Lower arm alarm output when the protection circuits are operating	

## 2 Description of Terminology

#### 1. Absolute Maximum Ratings

Term	Symbol	Description		
Bus voltage	V <sub>DC</sub>	DC voltage that can be applied between PN terminals		
DC Bus voltage	V <sub>DC</sub>	Peak value of the surge voltage that can be applied between PN		
(surge)	(surge)	terminals in switching		
DC Bus voltage (short circuit)	V <sub>SC</sub>	DC source voltage between PN terminals that can be protected from short circuits/overcurrent		
Collector-emitter Voltage	V <sub>CES</sub>	Maximum collector-emitter voltage of the built-in IGBT chip and repeated peak reverse voltage of the FWD chip (only the IGBT for the brake)		
Reverse voltage	V <sub>R</sub>	Repeated peak reverse voltage of the FWD chip in the brake section		
	Ι <sub>C</sub>	Maximum DC collector current for the IGBT chip		
Collector current	I <sub>CP</sub>	Maximum DC pulse collector current for the IGBT chip		
	-I <sub>C</sub>	Maximum DC forward current for the FWD chip		
FRD forward Current	I <sub>F</sub>	Maximum DC forward current for the FWD chip in the brake section		
Collector power Dissipation		Maximum power dissipation for one IGBT element Power dissipation for Tj to become 150°C at Tc = 25°C or power dissipated in collector so that Tj becomes 150°C at Tc = 25°C		
Control power source V <sub>cc</sub>		Voltage that can be applied between GND and each Vcc terminal		
Input voltage Vin		Voltage that can be applied between GND and each Vin terminal		
Input current	lin	Current that flows between GND and each Vin terminal		
Alarm signal voltage V <sub>ALM</sub>		Voltage that can be applied between GND and ALM terminal		
Alarm signal current	I <sub>ALM</sub>	Current that flows between GND and ALM terminal		
Chip junction Temperature		Maximum junction temperature of the IGBT and FWD chips during continuous operation		
Operating case Topr		Range of case temperature for electrical operation (Fig. 1 shows the measuring point of the case temperature Tc)		
Storage temperature T <sub>stg</sub>		Range of ambient temperature for storage or transportation, when there is no electrical load		
Isolating voltage Viso		Maximum effective value of the sine-wave voltage between the terminals and the heat sink, when all terminals are shorted simultaneously		
Screw Terminal	-	Max. torque for connection of terminal and external wire with the specified screw		
Mounting	-	Max. torque when mounting the element to the heat sink with the specified screw		

#### 2. Electrical Characteristics

#### 2.1 Main Circuit

Term	Symbol	Description
Collector-emitter cutoff current	I <sub>CES</sub>	Collector current when a specified voltage is applied between the collector and emitter of an IGBT with all input signals H (= Vz)
Collector-emitter saturation voltage	V <sub>CE</sub> (sat)	Collector-emitter voltage at a specified collector current when the input signal of only the elements to be measured is $L (= 0V)$ and the inputs of all other elements are H (= Vz)
Diode forward voltage	V <sub>F</sub>	Forward voltage at a specified forward current with all input signals H (= Vz)
Turn-on time	ton	The time from the input signal dropping below the threshold value until the collector current becomes 90% of the rating. See Fig. 2-3.
Turn-off time	toff	The time from the input signal rising above the threshold value until the collector current becomes 10% of the rating. See Fig. 2-3.
Fall time	tf	The time from the collector current becoming 90% at the time of IGBT turn-off until the tangent to the decreasing current becomes 10%. See Fig. 2-3.
Reverse recovery time	trr	The time required for the reverse recovery current of the built-in diode to disappear. See Fig. 2-3.

#### 2.2 Control Circuits

Term	Symbol	Description
Control power source	Ісср	Current flowing between control power source Vcc and GND on the P-side (upper arm side)
consumption current	lccn	Current flowing between control power source Vcc and GND on the N-side (lower arm side)
Input signal threshold	Vinth (on)	Control signal voltage when IGBT changes from OFF to ON
voltage	Vinth (off)	Control signal voltage when IGBT changes from ON to OFF
Input zenor voltage	Vz	Voltage clamped by zener diode connected between GND and each Vin when the control signal is OFF
Signal hold time	t <sub>ALM</sub>	Period in which an alarm continues to be output (ALM) from the ALM terminal after the N-side protection function is actuated
Limiting resistor for alarm	R <sub>ALM</sub>	Built-in resistance limiting the primary current of the photocoupler for ALM output
Current detection shunt resistance	R1	Resistance value of the IPM built-in shunt resistor (P617, P619)

#### 2.3 Protection Circuits

Term	Symbol	Description
Overcurrent protective operation current	I <sub>oc</sub>	IGBT collector current at which the overcurrent protection (OC) works
Overcurrent cut off time	t <sub>DOC</sub>	Shown in Fig. 2-1
Short-circuit protection delay time	tsc	Shown in Fig. 2-2
Chip overheating protection temperature	ТјоН	Tripping temperature at which the IGBT chip junction temperature Tj overheats and IGBT soft shutdown is performed
Chip overheating protection hysteresis	ТјН	Drop temperature required for output stop resetting after protection operation
Case overheating protection temperature	ТсОН	Tripping temperature at which the IGBT performs soft shutdown when the case temperature Tc shows overheating
Case overheating protection hysteresis	ТсН	Drop temperature required for output stop resetting after protection operation
Under voltage protection level	V <sub>UV</sub>	Tripping voltage at which the IGBT performs soft shutdown when the control power source voltage Vcc drops
Control power source undervoltage protection hysteresis	V <sub>H</sub>	Recovery voltage required for output stop resetting after protection operation

#### 3. Thermal Characteristics

Term	Symbol	Description
Chip-case thermal resistance	Rth (j-c)	Chip-case thermal resistance of IGBT or diode
Chip-fin thermal resistance	Rth (c-f)	Thermal resistance between the case and heat sink, when mounted on a heat sink at the recommended torque using the thermal compound
Case temperature	Тс	IPM case temperature (temperature of the copper plate directly under the IGBT or the diode)

#### 4. Noise Tolerance

Term	Symbol	Description
Common mode noise	-	Common mode noise tolerance in our test circuit
Electric surge	-	Electric surge tolerance in our test circuit

#### 5. Other

Term	Symbol	Description
Weight	Wt	Weight of IPM
Switching frequency	fsw	Range of control signal frequencies for input to the control signal input terminal
Reverse recovery current	Irr	Shown in Fig. 2-3
Reverse bias safe operation area	RBSOA	Area of the current and voltage in which IGBT can be cut off under specified conditions during turn-off
Switching loss	Eon	IGBT switching loss during turn-on
	Eoff	IGBT switching loss during turn-off
	Err	FWD switching loss during reverse recovery



Fig. 2-1 Overcurrent Protection Delay Time (tdoc)



Fig. 2-2 Short-circuit Protection Delay Time (tsc)





#### WARNING ------

<ol> <li>This Catalog contains the product spe The contents are subject to change wind Catalog, be sure to obtain the latest spectrum.</li> </ol>	cifications, characteristics, c thout notice for specification pecifications.	lata, materials, and s a changes or other re	tructures as of Februa asons. When using a	ary 2004. product listed in this
<ol> <li>All applications described in this Catal express or implied, under any patent, Technology Co., Ltd. is (or shall be de warranty, whether express or implied, may arise from the use of the applicat</li> </ol>	og exemplify the use of Fuji copyright, trade secret or ott emed) granted. Fuji Electric relating to the infringement ions described herein.	's products for your n ner intellectual prope c Device Technology or alleged infringeme	eference only. No righ rty right owned by Fuj Co., Ltd. makes no re ant of other's intellectu	nt or license, either i Electric Device spresentation or al property rights which
<ol> <li>Although Fuji Electric Device Technol products may become faulty. When u adequate safety measures to prevent become faulty. It is recommended to</li> </ol>	ogy Co., Ltd. is enhancing p sing Fuji Electric semicondu the equipment from causing make your design fail-safe,	roduct quality and re actor products in your a physical injury, fire flame retardant, and	liability, a small perce r equipment, you are r e, or other problem if a free of malfunction.	ntage of semiconductor equested to take any of the products
4. The products introduced in this Catalo	g are intended for use in the	e following electronic	and electrical equipm	ent which has
- Computers	• Communications	quinmont (torminal c		ouromont oquipmont
Machine tools     Audiovisual equip	• Electrical home	appliances • Per	sonal equipment	Industrial robots etc.
<ul> <li>5. If you need to use a product in this Ca below, it is imperative to contact Fuji E such equipment, take adequate meas product incorporated in the equipment</li> <li>Transportation equipment (mounted</li> <li>Traffic-signal control equipment</li> <li>Emergency equipment for responding</li> </ul>	Italog for equipment requirin Electric Device Technology ( ures such as a backup syste becomes faulty. on cars and ships) g to disasters and anti-burg	g higher reliability th. Co., Ltd. to obtain pri em to prevent the eq • Trunk commur • Gas leakage d lary devices	an normal, such as for or approval. When us uipment from malfunc nications equipment etectors with an auto- • Safety der	r the equipment listed ing these products for tioning even if a Fuji's shut-off feature vices
6. Do not use products in this Catalog fo	r the equipment requiring st	rict reliability such as	(without limitation)	
Space equipment	<ul> <li>Aeronautic equipment</li> </ul>	Nuclear co	ntrol equipment	
Submarine repeater equipment	<ul> <li>Medical equipment</li> </ul>			
<ol> <li>Copyright © 1996-2004 by Fuji Electri No part of this Catalog may be reprod Technology Co., Ltd.</li> </ol>	c Device Technology Co., L uced in any form or by any i	td. All rights reserve means without the ex	d. xpress permission of F	uji Electric Device
8. If you have any question about any po using the product.	ortion in this Catalog, ask Fu	iji Electric Device Te	chnology Co., Ltd. or i	its sales agents before
Neither Fuji Electric Device Technolog accordance with instructions set forth	gy Co., Ltd. nor its agents sh herein.	hall be liable for any i	injury caused by any t	use of the products not in